

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	BSC030N04NS G	**Issued**	4. October 2018
MA#	MA001837566		
Package	PG-TDSON-8-39	**Weight***	112.99 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.391	2.12	2.12	21163	21163
leadframe	inorganic material	phosphorus	7723-14-0	0.015	0.01		129	
	non noble metal	iron	7439-89-6	0.048	0.04		429	
	non noble metal	copper	7440-50-8	48.352	42.79	42.84	427952	428510
wire	non noble metal	copper	7440-50-8	0.042	0.04	0.04	368	368
encapsulation	organic material	carbon black	1333-86-4	0.082	0.07		722	
	plastics	epoxy resin	-	6.447	5.71		57061	
	inorganic material	silicondioxide	60676-86-0	34.275	30.34	36.12	303360	361143
leadfinish	non noble metal	tin	7440-31-5	1.520	1.35	1.35	13453	13453
plating	noble metal	silver	7440-22-4	0.158	0.14	0.14	1402	1402
solder	non noble metal	tin	7440-31-5	0.046	0.04		403	
	noble metal	silver	7440-22-4	0.057	0.05		503	
	non noble metal	lead	7439-92-1	2.173	1.92	2.01	19232	20138
heatspreader	inorganic material	phosphorus	7723-14-0	0.000	0.00		1	
	non noble metal	iron	7439-89-6	0.000	0.00		3	
	non noble metal	copper	7440-50-8	0.297	0.26	0.26	2630	2634
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.005	0.00		45	
	non noble metal	iron	7439-89-6	0.017	0.02		150	
	noble metal	silver	7440-22-4	0.150	0.13		1328	
	non noble metal	copper	7440-50-8	16.910	14.97	15.12	149666	151189
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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